FOR IMMEDIATE RELEASE

STATS ChipPAC Honours Top Suppliers for Excellent Performance and Outstanding Support

Singapore – 6 August 2014 – STATS ChipPAC Ltd. ("STATS ChipPAC" or the "Company" – SGX-ST: STATSChP) today announced the recipients of its seventh annual Supplier Awards, honouring the excellent performance and outstanding contributions of the Company's top suppliers in 2013.

STATS ChipPAC's top honour, "Best Supplier Award", was given to four suppliers for overall best-in-class performance in cost, quality, delivery, technology, service and support. Six suppliers were recognised with an "Outstanding Award in Service and Support" for excellence in service, support and responsiveness. For their outstanding service and support for a particular STATS ChipPAC manufacturing site, four companies received "Outstanding Site Award in Service and Support".

The winners by category are:

Best Supplier Award

- Daewon SPIC/Peak International
- DISCO Corporation
- Kinsus Interconnect Technology Corporation
- NAMICS Corporation

Outstanding Award in Service and Support

- Advantest Corporation
- Duksan Hi-Metal Co., Ltd.
- Kulicke & Soffa Industries, Inc.
- Lam Research Corporation
- Mitsui High-tec, Inc.
- Teradyne, Inc.

Outstanding Site Award in Service and Support

- Hon. Technologies, Inc. (for STATS ChipPAC Shanghai)
- Oriental Mercury International Cargo Transportation Co., Ltd. (for STATS ChipPAC Shanghai)
- SUSS MicroTec AG (for STATS ChipPAC Singapore)
- UBoT Incorporated Limited (for STATS ChipPAC Shanghai)

"The strong relationships we have with our suppliers are vital to our business and enable us to deliver compelling advantages to our customers in cost effective, high quality packaging and test solutions. With our strategic focus on advanced flip chip and wafer level packaging turnkey solutions, it is critical that our suppliers are well-aligned with our technology roadmap and are able to respond quickly to our customers' time-to-market requirements," said Cindy Palar, Senior Vice President of Strategic Operations, STATS ChipPAC. "We are pleased to recognise our top suppliers' outstanding achievements and congratulate each of them for a job well done."

STATS ChipPAC Ltd.
Company Registration No.: 199407932D
Headquarters: 10 Ang Mo Kio Street 65, #05-17/20 Techpoint, Singapore 569059
www.statschippac.com

About STATS ChipPAC Ltd.

STATS ChipPAC Ltd. (SGX-ST Code: S24) is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development, manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com. Information contained in this website does not constitute a part of this release.

Investor Relations Contact:
Tham Kah Locke
Vice President of Corporate Finance
Tel: (65) 6824 7788, Fax: (65) 6720 7826
email: kahlocke.tham@statschippac.com

Media Contact:
Lisa Lavin
Deputy Director of Marketing Communications
Tel: (208) 867-9859
email: lisa.lavin@statschippac.com